

Amendments to the Claims

Please amend the claims as follows.

1. (Currently Amended) A semiconductor device comprising:
a semiconductor chip, which produces heat when operated;
~~a pair of~~ heat conducting ~~plates~~ plate for conducting heat ~~from opposite surfaces of~~
~~the~~ provided on one side of the semiconductor chip, wherein the plates face each other;
~~a pair of an~~ insulating ~~sheets~~ sheet, which ~~are~~ is compressively deformable, ~~adhered to~~
~~the heat conducting plates also provided on the one side of the semiconductor chip; and~~
a resin molding covering the semiconductor chip, the ~~plates~~ plate, and the ~~sheets~~ sheet
such that the ~~sheets~~ sheet ~~are~~ is exposed from the resin molding.

2. (Currently Amended) The semiconductor device of claim 1, wherein the heat conductivity of the insulating ~~sheets~~ sheet is greater than that of the resin molding.

3. (Currently Amended) The semiconductor device of claim 2, wherein the insulating ~~sheets are~~ sheet is made of silicone rubber.

4-6 (Canceled)

7. (Currently Amended) The semiconductor device of claim 1, wherein the insulating ~~sheets are~~ sheet is adhered to the heat sinks conducting plate using a coating resin applied to ~~the surfaces of the heat sinks~~ heat conducting plate.

8. (Original) The semiconductor device of claim 7, wherein the coating resin is polyamide resin.

9. (Currently Amended) The semiconductor device of claim 1, wherein the semiconductor chip forms part of a stack, and the stack includes the ~~plates~~ plate, and opposite sides of the semiconductor chip are soldered to members of the stack.

10-16. (Canceled)